Special Issue on Packaging Materials Research

Call for Papers

Packaging is the technology that encloses or protects products for the purpose of distribution, storage, sale, and use. The process of design, evaluation, and production of packages also mean packaging. Packaging can be described as a coordinated system of preparing goods for transport, warehousing, logistics, sale, and end use. However, packaging materials are very important to packaging. Packaging material is also a hot spot research problem. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of packaging materials research.

In this special issue, we invite front-line researchers and authors to submit original research and review articles that explore packaging materials research. In this special issue, potential topics include, but are not limited to:

- Package labeling
- Packaging types
- Shipping container labeling
- Plastic packaging
- Sustainable packaging
- Packaging machines

Authors should read over the journal’s Authors’ Guidelines carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal’s Paper Submission System.

Please kindly notice that the “Special Issue” under your manuscript title is supposed to be specified and the research field “Special Issue - Packaging Materials Research” should be chosen during your submission.

According to the following timetable:

| Submission Deadline | June 5th, 2014 |
| Publication Date    | August 2014    |

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